

APTB1615SURKSGC

HYPER RED

SUPER BRIGHT GREEN

Features

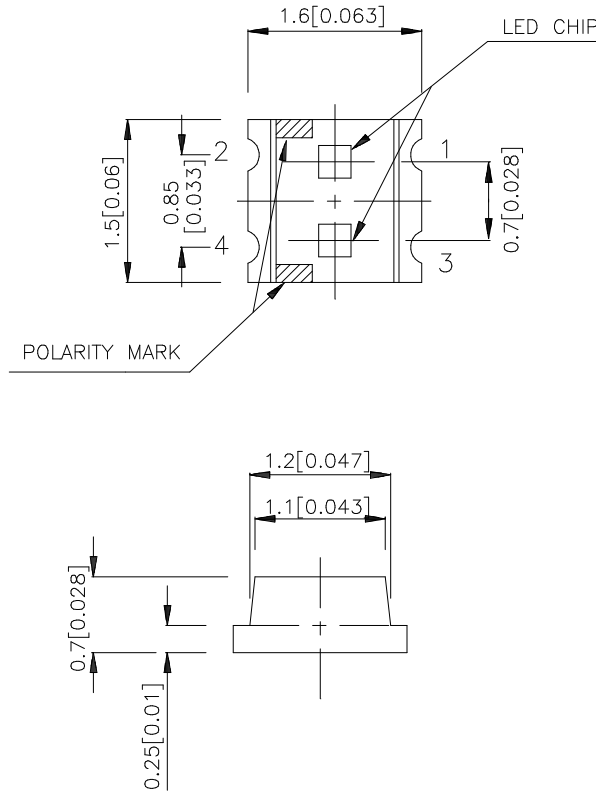
- 1.6mmx1.5mm SMT LED, 0.7mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 (0.008") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APT B1615SURKSGC	HYPER RED (InGaAlP)	WATER CLEAR	70	150	120°
	SUPER BRIGHT GREEN (GaP)		2.6	12	

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

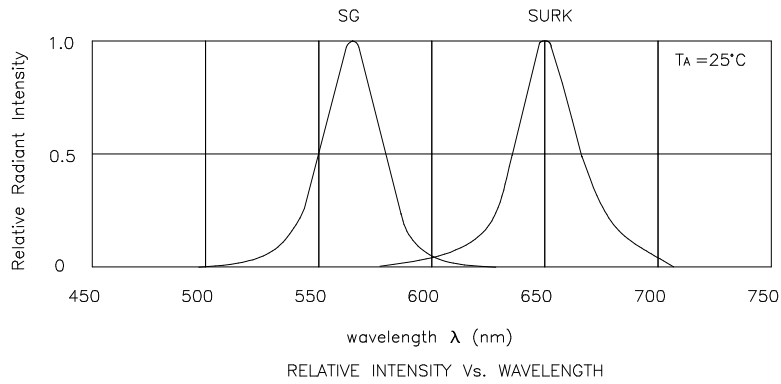
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red Super Bright Green	650 565		nm	I _F =20mA
λ _D	Dominate Wavelength	Hyper Red Super Bright Green	635 568		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Hyper Red Super Bright Green	28 30		nm	I _F =20mA
C	Capacitance	Hyper Red Super Bright Green	35 15		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Hyper Red Super Bright Green	1.95 2.2	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	All		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Hyper Red	Super Bright Green	Units
Power dissipation	170	105	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	185	140	mA
Reverse Voltage	5	5	V
Operating/Storage Temperature	-40°C To +85°C		

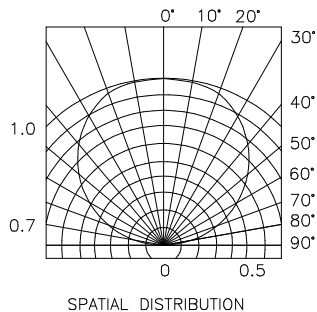
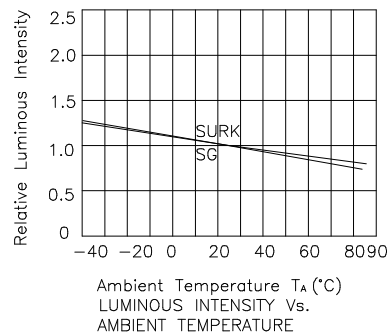
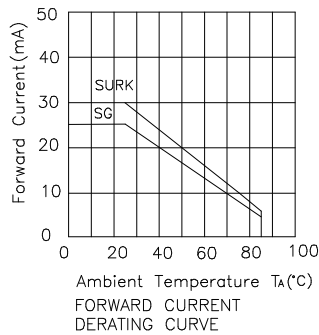
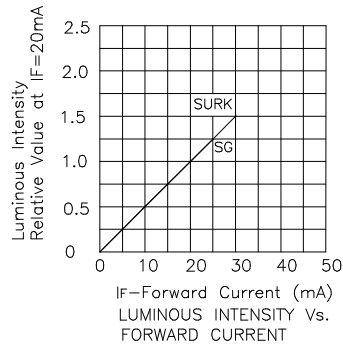
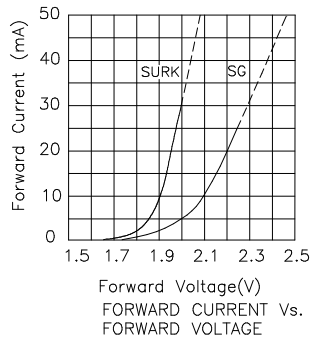
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



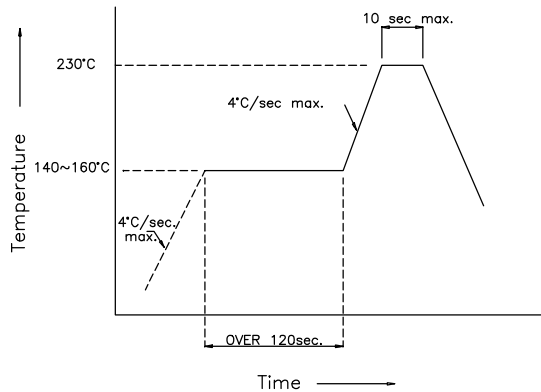
Hyper Red / Super Bright Green

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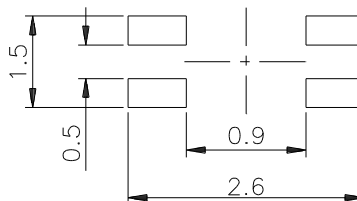


APTB1615SURKSGC SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

